



R-6789-90

B. E. III (Sem. V) (EC/ECC) Examination
May / June - 2007
Digital Micro Electronics

Time : 3 Hours]

[Total Marks : 100]

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Instructions :

(1)

नीचे दिए गए नियमों के सभी पर अवश्य लगवा।
Fillup strictly the details of signs on your answer book.

Name of the Examination : **B. E. 3 (Sem. 5) (EC/ECC)**

Name of the Subject : **Digital Micro Electronics**

Subject Code No.: **6 7 8 9** Section No. (1, 2,) : **1**

Seat No.:

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Student's Signature

(2) Attempt all questions.

(3) Figures on right indicate full marks.

(4) Assume suitable data if required.

1 (a) Attempt the following : 10

- (1) Define fanout 141
- (2) Define propagation delay 161
- (3) State the disadvantage of DCTL logic family
- (4) Fanout of the ECL gate is highest. (State true/false)
- (5) What is the function of diode connected between inputs and ground in TTL ?
- (6) State the advantage of HTL over DTL.
- (7) What is active pull up ?
- (8) Among TTL and ECL which family has higher power dissipation ? ECL
- (9) State true/false : DTL is faster than TTL
- (10) TTL is different from RTL and DTL (State true/false)

(b) (i) Explain current hogging phenomenon in DCTL. 5

(ii) Explain the methods to remove the propagation delay hazards with diagram. 5

2 (a) Draw and explain RTL NOR gate. Discuss the manufacturer's specification of RTL gates in detail. 7

R-6789-90]

1

[Contd...]

(b) Draw and explain HTL NAND gate with its transfer characteristics. Also explain that the temperature sensitivity of HTL is better than DTL. 8

OR

2 (a) Draw and explain two input IC DTL NAND gate. 7

(b) Explain the basic configuration of I^2L family. 8

3 Attempt any two :

(1) Draw and explain standard two input TTL NAND gate.

(2) Calculate the static fanout for the circuit shown in Fig. 1. Assume that the NOR output voltage can drop from its nominal (high) value of $-0.7V$ by $\Delta V = 50 \text{ mV}$.

Use $\beta = 100$.

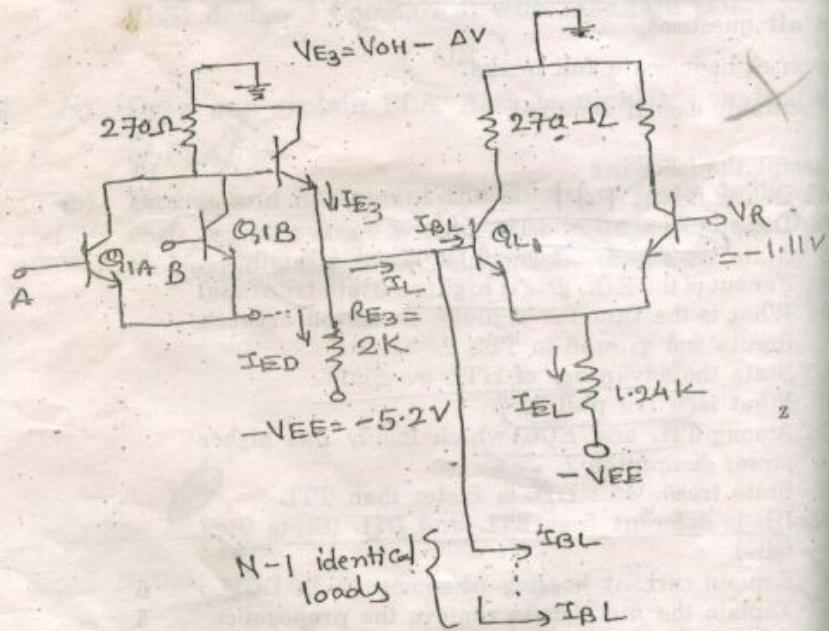


Fig. 1

(3) Explain the basic principle of ECL gate and draw an ECL NOR gate.

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[Contd.]

R-6789-90]

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Instructions :

(1)

मार्ग दर्शक का नियानीकारी विज्ञों परावर्ती पर अवश्य लगायें।
Fill up strictly the details of \rightarrow signs on your answer book.

Name of the Examination :

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Name of the Subject :

\rightarrow Digital Micro Electronics

Subject Code No.

6

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9

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\rightarrow

Section No. (1, 2, ...,)

Seat No.:

Student's Signature

(2) Attempt all questions.

(3) Figures on right indicate full marks.

10

(4) Assume suitable data if required.

4 (a) Attempt any five : (each of 2 marks)

$$V_{OH} > V_{IH}, V_{OL} > V_{IL}$$

10

\rightarrow (1) Mention interfacing criteria to interface TTL CMOS ckt.

$$I_{OH} > N_i I_H$$

(2) What is the importance of W/L ratio in CMOS inverter?

$$I_{OL} > N_o I_L$$

(3) What is BiCMOS Totem-pole gate? What does transition do at output stage of circuit?

$$IC$$

(4) Why MOS logic is mainly used for LSI and VLSI applications? \rightarrow cheap, small sizes, reliable device

(5) Some information is stored in an EPROM, which is required to be modified, how will you do it?

(6) Differentiate between random access memory and sequentially accessed memory from the point of view of speed of operation.

(7) What are the main advantages of using PLAs for realizing combinational logic function over logic gates? \rightarrow In PLA we imp. the fct. w.r.t. to logic

(b) Compare TTL, BiCMOS and CMOS logic family with respect to propagation delay and power dissipation.

6

Describe the importance of the bleeder resistors in BiCMOS inverter circuit with proper circuit diagram.

TOP

(c) Calculate the rise time of N channel MOSFET. If load capacitance is 5 PF

CMOS P.D.L

\rightarrow Transconductance parameter is $20 \mu A/V^2$

4 TTL P.D.L

Supply voltage is 12 V

BiCMOS P.D.L

Threshold voltage is 0.7 V

$$t_{Rise} = \frac{g_{m} C_L}{K_L V_F}$$

R-6789-90] \rightarrow $V_f = V_{SBP} - V_T$

[Contd...

$$V_f = V_{SBP} - V_T$$

~~Ques~~ 5 (a) Design and implement the following Boolean expression using PMOS and also list out No. of transistors required for implementations

(1) $V_D = \bar{A} \cdot (\bar{B} + C)$

$\boxed{\bar{A} \cdot (\bar{B} + C)}$

(2) $V_D = \bar{A} + \bar{B} \bar{C}$

$\boxed{\bar{A} + \bar{B} \bar{C}}$

(b) What is memory refreshing? Which type of transistor RAM cell use refresh circuit? Draw and explain such a cell with its proper working.

OR

5 (a) Explain rise time and fall time in CMOS gate.

8

(b) It is desired to combine separate $2 \text{ k} \times 8$ PROM to produce a total capacity of $8 \text{ k} \times 8$. How many PROM chips are needed? How many address bus lines are required?

5

(c) Draw NMOS NAND gate.

2

6 (a) Which parameter in fabrication play an important role to make an erasable PROM? Explain the construction and working of EPROM.

7

(b) Draw the structure of the circuit which requires programmable AND gates and programmable OR gates. Explain its operations in brief.

8

OR

6 (a) Explain programmable logic device need. What is the significance of CMOS logic family in VLSI design? Explain CMOS gate array approach with an appropriate diagram.

8

(b) Draw and explain DRAM one bit transistor memory cell.

R-6789-90]